~~What is claimed is:~~

1. A method for manufacturing a reticle system comprising:

providing a reticle system; and

assigning two or more of an image pattern onto the reticle system to form one or more layers of an integrated circuit system by grouping and pairing each of the image pattern onto the reticle system according to a multi-layer reticle grouping/pairing flow.

2. The system as claimed in claim 1 wherein:

assigning two or more of the image pattern onto the reticle system inlcudes analyzing information from a data group, a reticle process group, a reticle specification group, a wafer process group, or a combination thereof.

3. The system as claimed in claim 1 wherein:

assigning two or more of the image pattern onto the reticle system inlcudes analyzing information from a data group including a reticle polarity factor, a frame structure polarity factor, a scribe line polarity factor, a reticle transmission percent factor, a disposition structure factor, or a combination thereof.

4. The system as claimed in claim 1 wherein:

assigning two or more of the image pattern onto the reticle system inlcudes analyzing information from a reticle process group including a reticle type factor, a reticle resist blank factor, a pellicle type factor, a writer type factor, a cleaning type factor, or a combination thereof.

5. The system as claimed in claim 1 wherein:

assigning two or more of the image pattern onto the reticle system inlcudes analyzing information from a reticle specification group including a reticle requirement factor, a reticle grade factor, or a combination thereof.

6. The system as claimed in claim 1 wherein:

assigning two or more of the image pattern onto the reticle system inlcudes analyzing information from a wafer process group including a machine type factor, an inspection/storage factor, or a combination thereof.

~~7. A method for manufacturing a reticle system comprising:~~

providing a reticle system; and

assigning two or more of a sub-pattern onto the reticle system to form a target pattern within an integrated circuit system by grouping and pairing each of the sub-pattern onto the reticle system according to a multi-layer reticle grouping/pairing flow.

8. The system as claimed in claim 7 wherein:

assigning two or more of the sub-pattern onto the reticle system inlcudes analyzing information from a data group, a reticle process group, a reticle specification group, a wafer process group, or a combination thereof.

9. The system as claimed in claim 7 wherein:

assigning two or more of the sub-pattern onto the reticle system inlcudes analyzing information from a data group including a reticle polarity factor, a frame structure polarity factor, a scribe line polarity factor, a reticle transmission percent factor, a disposition structure factor, or a combination thereof.

10. The system as claimed in claim 7 wherein:

assigning two or more of the sub-pattern onto the reticle system inlcudes analyzing information from a reticle process group including a reticle type factor, a reticle resist blank factor, a pellicle type factor, a writer type factor, a cleaning type factor, or a combination thereof.

11. The system as claimed in claim 7 wherein:

assigning two or more of the sub-pattern onto the reticle system inlcudes analyzing information from a reticle specification group including a reticle requirement factor, a reticle grade factor, or a combination thereof.

12. The system as claimed in claim 7 wherein:

assigning two or more of the sub-pattern onto the reticle system inlcudes analyzing information from a wafer process group including a machine type factor, an inspection/storage factor, or a combination thereof.

13. A method for manufacturing a reticle system comprising:

providing a reticle system; and

assigning two or more of an image pattern onto the reticle system to form one or more layers of an integratged circuit system by grouping and pairing each of the

image pattern onto the reticle system according to a reticle transmission percent factor not exceeding a differnce of twenty percent between each of the image pattern.

14. A method for manufacturing a reticle system comprising:

providing a reticle system; and

assigning two or more of a sub-pattern onto the reticle system to form a target pattern within an integrated circuit system by grouping and pairing each of the sub-pattern onto the reticle system according to a reticle transmission percent factor not exceeding a difference of twenty percent between each of the sub-pattern.

15. A method for manufacturing a reticle system comprising:

providing a reticle system; and

assigning two or more of an image pattern onto the reticle system to form one or more layers of an integratged circuit system by grouping and pairing each of the image pattern onto the reticle system according to a disposition structure factor of lines and spaces or holes.

16. A method for manufacturing a reticle system comprising:

providing a reticle system; and

assigning two or more of a sub-pattern onto the reticle system to form a target pattern within an integrated circuit system by grouping and pairing each of the sub-pattern onto the reticle system according to a disposition structure factor of lines and spaces or holes.

17. A method for manufacturing an integrated circuit system comprising:

providing a reticle system;

assigning two or more of an image pattern onto the reticle system by grouping and pairing each of the image pattern onto the reticle system according to a multi-layer reticle grouping/pairing flow; and

using the reticle system in a photolithography system to form one or more layers of an integratged circuit system.

~~18. The system as claimed in claim 17 wherein:~~

assigning two or more of the image pattern onto the reticle system inlcudes analyzing information from a data group, a reticle process group, a reticle specification group, a wafer process group, or a combination thereof.

19. The system as claimed in claim 17 wherein:

assigning two or more of the image pattern onto the reticle system inlcudes analyzing information from a data group including a reticle polarity factor, a frame structure polarity factor, a scribe line polarity factor, a reticle transmission percent factor, a disposition structure factor, or a combination thereof.

20. The system as claimed in claim 17 wherein:

assigning two or more of the image pattern onto the reticle system inlcudes analyzing information from a reticle process group including a reticle type factor, a reticle resist blank factor, a pellicle type factor, a writer type factor, a cleaning type factor, or a combination thereof.

21. The system as claimed in claim 17 wherein:

assigning two or more of the image pattern onto the reticle system inlcudes analyzing information from a reticle specification group including a reticle requirement factor, a reticle grade factor, or a combination thereof.

22. The system as claimed in claim 17 wherein:

assigning two or more of the image pattern onto the reticle system inlcudes analyzing information from a wafer process group including a machine type factor, an inspection/storage factor, or a combination thereof.

23. A method for manufacturing an integrated circuit system comprising:

providing a reticle system;

assigning two or more of a sub-pattern onto the reticle system by grouping and pairing each of the sub-pattern onto the reticle system according to a multi-layer reticle grouping/pairing flow; and

using the reticle system in a photolithography system to form a target pattern within an integrated circuit system.

~~24. The system as claimed in claim 23 wherein:~~

assigning two or more of the sub-pattern onto the reticle system inlcudes analyzing information from a data group, a reticle process group, a reticle specification group, a wafer process group, or a combination thereof.

25. The system as claimed in claim 23 wherein:

assigning two or more of the sub-pattern onto the reticle system inlcudes analyzing information from a data group including a reticle polarity factor, a frame structure polarity factor, a scribe line polarity factor, a reticle transmission percent factor, a disposition structure factor, or a combination thereof.

26. The system as claimed in claim 23 wherein:

assigning two or more of the sub-pattern onto the reticle system inlcudes analyzing information from a reticle process group including a reticle type factor, a reticle resist blank factor, a pellicle type factor, a writer type factor, a cleaning type factor, or a combination thereof.

27. The system as claimed in claim 23 wherein:

assigning two or more of the sub-pattern onto the reticle system inlcudes analyzing information from a reticle specification group including a reticle requirement factor, a reticle grade factor, or a combination thereof.

28. The system as claimed in claim 23 wherein:

assigning two or more of the sub-pattern onto the reticle system inlcudes analyzing information from a wafer process group including a machine type factor, an inspection/storage factor, or a combination thereof.

29. A photolithography system comprising:

providing a reticle system; and

assigning two or more of an image pattern onto the reticle system to form one or more layers of an integrated circuit system by grouping and pairing each of the image pattern onto the reticle system according to a multi-layer reticle grouping/pairing flow.

30. The system as claimed in claim 29 further comprising:

~~an integrated circuit device manufactured using the photolithography system.~~

31. A photolithography system comprising:

providing a reticle system; and

assigning two or more of a sub-pattern onto the reticle system to form a target pattern within an integrated circuit system by grouping and pairing each of the sub-pattern onto the reticle system according to a multi-layer reticle grouping/pairing flow.

32. The system as claimed in claim 31 further comprising:

an integrated circuit device manufactured using the photolithography system.

What is claimed is:

1. A method for manufacturing a reticle system comprising:

providing a reticle system; and

assigning two or more of an image pattern onto the reticle system to form one or more layers of an integrated circuit system by grouping and pairing each of the image pattern onto the reticle system according to a multi-layer reticle grouping/pairing flow that utilizes grouping and pairing factors.

2. The method as claimed in claim 1 wherein:

assigning two or more of the image pattern onto the reticle system inlcudes analyzing information from a data group, a reticle process group, a reticle specification group, a wafer process group, or a combination thereof.

3. The method as claimed in claim 1 wherein:

assigning two or more of the image pattern onto the reticle system inlcudes analyzing information from a data group including a reticle polarity factor, a frame structure polarity factor, a scribe line polarity factor, a reticle transmission percent factor, a disposition structure factor, or a combination thereof.

4. The method as claimed in claim 1 wherein:

assigning two or more of the image pattern onto the reticle system inlcudes analyzing information from a reticle process group including a reticle type factor, a reticle resist blank factor, a pellicle type factor, a writer type factor, a cleaning type factor, or a combination thereof.

5. The method as claimed in claim 1 wherein:

assigning two or more of the image pattern onto the reticle system inlcudes analyzing information from a reticle specification group including a reticle requirement factor, a reticle grade factor, or a combination thereof.

6. The method as claimed in claim 1 wherein:

assigning two or more of the image pattern onto the reticle system inlcudes analyzing information from a wafer process group including a machine type factor, an inspection/storage factor, or a combination thereof.

7. A method for manufacturing a reticle system comprising:

providing a reticle system; and

assigning two or more of a sub-pattern onto the reticle system to form a target pattern within an integrated circuit system by grouping and pairing each of the sub-pattern onto the reticle system according to a multi-layer reticle grouping/pairing flow that utilizes grouping and pairing factors.

8. The method as claimed in claim 7 wherein:

assigning two or more of the sub-pattern onto the reticle system inlcudes analyzing information from a data group, a reticle process group, a reticle specification group, a wafer process group, or a combination thereof.

9. The method as claimed in claim 7 wherein:

assigning two or more of the sub-pattern onto the reticle system inlcudes analyzing information from a data group including a reticle polarity factor, a frame structure polarity factor, a scribe line polarity factor, a reticle transmission percent factor, a disposition structure factor, or a combination thereof.

10. The method as claimed in claim 7 wherein:

assigning two or more of the sub-pattern onto the reticle system inlcudes analyzing information from a reticle process group including a reticle type factor, a reticle resist blank factor, a pellicle type factor, a writer type factor, a cleaning type factor, or a combination thereof.

11. The method as claimed in claim 7 wherein:

assigning two or more of the sub-pattern onto the reticle system inlcudes analyzing information from a reticle specification group including a reticle requirement factor, a reticle grade factor, or a combination thereof.

12. The method as claimed in claim 7 wherein:

assigning two or more of the sub-pattern onto the reticle system inlcudes analyzing information from a wafer process group including a machine type factor, an inspection/storage factor, or a combination thereof.

13. A method for manufacturing a reticle system comprising:

providing a reticle system; and

assigning two or more of an image pattern onto the reticle system to form one or more layers of an integrated circuit system by grouping and pairing each of the image pattern onto the reticle system according to grouping and pairing factors including a reticle transmission percent factor not exceeding a difference of twenty percent between each of the image pattern.

14. A method for manufacturing a reticle system comprising:

providing a reticle system; and

assigning two or more of a sub-pattern onto the reticle system to form a target pattern within an integrated circuit system by grouping and pairing each of the sub-pattern onto the reticle system according to grouping and pairing factors including a reticle transmission percent factor not exceeding a difference of twenty percent between each of the sub-pattern.

15. A method for manufacturing a reticle system comprising:

providing a reticle system; and

assigning two or more of an image pattern onto the reticle system to form one or more layers of an integratged circuit system by grouping and pairing each of the image pattern onto the reticle system according to grouping and pairing factors including a disposition structure factor of lines and spaces or holes.

16. A method for manufacturing a reticle system comprising:

providing a reticle system; and

assigning two or more of a sub-pattern onto the reticle system to form a target pattern within an integrated circuit system by grouping and pairing each of

the sub-pattern onto the reticle system according to grouping and pairing factors including a disposition structure factor of lines and spaces or holes.

17. A method for manufacturing an integrated circuit system comprising:

providing a reticle system;

assigning two or more of an image pattern onto the reticle system by grouping and pairing each of the image pattern onto the reticle system according to a multi-layer reticle grouping/pairing flow that utilizes grouping and pairing factors; and

using the reticle system in a photolithography system to form one or more layers of an integrated circuit system.

18. The method as claimed in claim 17 wherein:

assigning two or more of the image pattern onto the reticle system inlcudes analyzing information from a data group, a reticle process group, a reticle specification group, a wafer process group, or a combination thereof.

19. The method as claimed in claim 17 wherein:

assigning two or more of the image pattern onto the reticle system inlcudes analyzing information from a data group including a reticle polarity factor, a frame structure polarity factor, a scribe line polarity factor, a reticle transmission percent factor, a disposition structure factor, or a combination thereof.

20. The method as claimed in claim 17 wherein:

assigning two or more of the image pattern onto the reticle system inlcudes analyzing information from a reticle process group including a reticle type factor, a reticle resist blank factor, a pellicle type factor, a writer type factor, a cleaning type factor, or a combination thereof.

21. The method as claimed in claim 17 wherein:

assigning two or more of the image pattern onto the reticle system inlcudes analyzing information from a reticle specification group including a reticle requirement factor, a reticle grade factor, or a combination thereof.

22. The method as claimed in claim 17 wherein:

assigning two or more of the image pattern onto the reticle system inlcudes analyzing information from a wafer process group including a machine type factor, an inspection/storage factor, or a combination thereof.

23. A method for manufacturing an integrated circuit system comprising:

providing a reticle system;

assigning two or more of a sub-pattern onto the reticle system by grouping and pairing each of the sub-pattern onto the reticle system according to a multi-layer reticle grouping/pairing flow that utilizes grouping and pairing factors; and

using the reticle system in a photolithography system to form a target pattern within an integrated circuit system.

24. The method as claimed in claim 23 wherein:

assigning two or more of the sub-pattern onto the reticle system inlcudes analyzing information from a data group, a reticle process group, a reticle specification group, a wafer process group, or a combination thereof.

25. The method as claimed in claim 23 wherein:

assigning two or more of the sub-pattern onto the reticle system inlcudes analyzing information from a data group including a reticle polarity factor, a frame structure polarity factor, a scribe line polarity factor, a reticle transmission percent factor, a disposition structure factor, or a combination thereof.

26. The method as claimed in claim 23 wherein:

assigning two or more of the sub-pattern onto the reticle system inlcudes analyzing information from a reticle process group including a reticle type factor, a reticle resist blank factor, a pellicle type factor, a writer type factor, a cleaning type factor, or a combination thereof.

27. The method as claimed in claim 23 wherein:

assigning two or more of the sub-pattern onto the reticle system inlcudes analyzing information from a reticle specification group including a reticle requirement factor, a reticle grade factor, or a combination thereof.

28. The method as claimed in claim 23 wherein:

assigning two or more of the sub-pattern onto the reticle system inlcudes analyzing information from a wafer process group including a machine type factor, an inspection/storage factor, or a combination thereof.

29. A photolithography system comprising:

providing a reticle system; and

assigning two or more of an image pattern onto the reticle system to form one or more layers of an integrated circuit system by grouping and pairing each of the image pattern onto the reticle system according to a multi-layer reticle grouping/pairing flow that utilizes grouping and pairing factors.

30. The system as claimed in claim 29 further comprising:

an integrated circuit device manufactured using the photolithography system.

31. A photolithography system comprising:

providing a reticle system; and

assigning two or more of a sub-pattern onto the reticle system to form a target pattern within an integrated circuit system by grouping and pairing each of the sub-pattern onto the reticle system according to a multi-layer reticle grouping/pairing flow that utilizes grouping and pairing factors.

32. The system as claimed in claim 31 further comprising:

an integrated circuit device manufactured using the photolithography system.